

ABSTRACT OF THE DISCLOSURE

An electronic device includes a substrate, a lower
conductive film formed on the substrate and a functional
5 film formed on the lower conductive film. In the present
invention, an adhesion of the lower conductive film on the
side of the substrate is greater than or equal to 0.1 N/cm.
The electronic device according to this invention exhibits
high mechanical strength that makes it very reliable.
10 This is because the invention prevents the physical
exfoliation of the lower conductive film that is apt to
occur during or after fabrication of the electronic device
when the adhesion of the lower conductive film is lower
than 0.1 N/cm.